

## P-Channel Enhancement Mode Power MOSFET

### Description

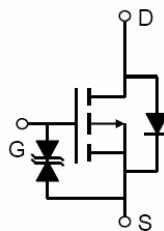
The PTF1UF060 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. It is ESD protected.

### General Features

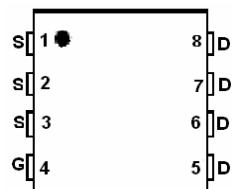
- $V_{DS} = -100V, I_D = -1A$
- $R_{DS(ON)} < 58m\Omega @ V_{GS} = -10V$  (Typ:44mΩ)
- $R_{DS(ON)} < 65m\Omega @ V_{GS} = -4.5V$  (Typ:48mΩ)
- Super high dense cell design
- Advanced trench process technology
- Reliable and rugged
- High density cell design for ultra low On-Resistance

### Application

- Portable equipment and battery powered systems



Schematic diagram



Marking and pin assignment

**100% UIS TESTED!**

**100% ΔVds TESTED!**

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PTF1UF060	PTF1UF060	TO-220AB			-

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-1A	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	-0.8A	A
Pulsed Drain Current	$I_{DM}$	1A	A
Maximum Power Dissipation	$P_D$	120	W
Derating factor		0.8	W/ $^\circ C$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	$^\circ C$

### Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	$R_{\theta Jc}$	1.25	$^\circ C/W$
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**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

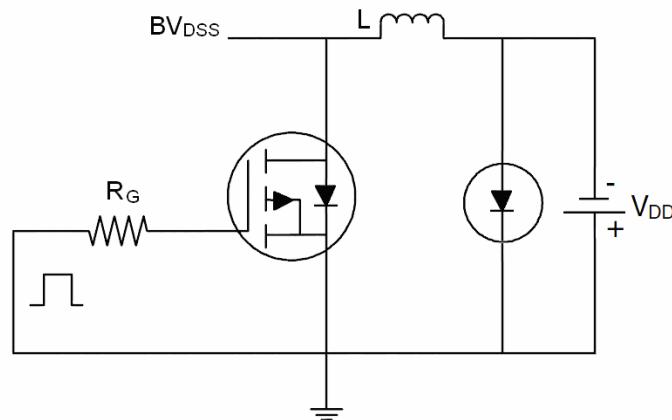
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-100	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=-100\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm10$	$\mu\text{A}$
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.5	-1.9	-2.5	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-15\text{A}$	-	44	58	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-15\text{A}$	-	48	65	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-10\text{A}$	5	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=-50\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	3810	-	PF
Output Capacitance	$C_{\text{oss}}$		-	93	-	PF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	91	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-50\text{V}, I_{\text{D}}=-15\text{A}$ $V_{\text{GS}}=-10\text{V}, R_{\text{GEN}}=9.1\Omega$	-	17	-	nS
Turn-on Rise Time	$t_r$		-	80	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	45	-	nS
Turn-Off Fall Time	$t_f$		-	65	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=-50\text{V}, I_{\text{D}}=-15\text{A}, V_{\text{GS}}=-10\text{V}$	-	136	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	22	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	26	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-10\text{A}$	-	-	-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_{\text{S}}$	-	-	-	-F	A
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = 25^\circ\text{C}, IF = -15\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ <sup>(Note 3)</sup>	-	90	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	70	-	nC
Forward Turn-On Time	$t_{\text{on}}$	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

**Notes:**

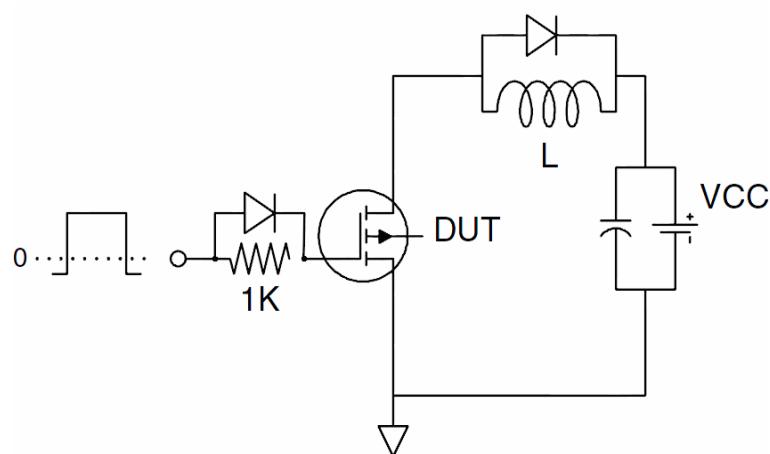
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

## Test Circuit

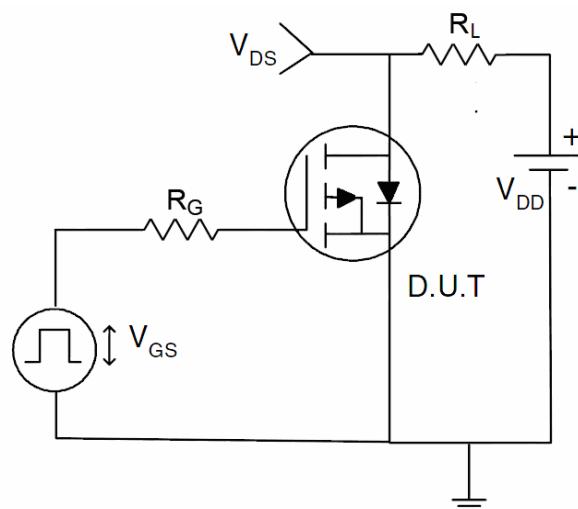
## 1) E<sub>AS</sub> Test Circuit



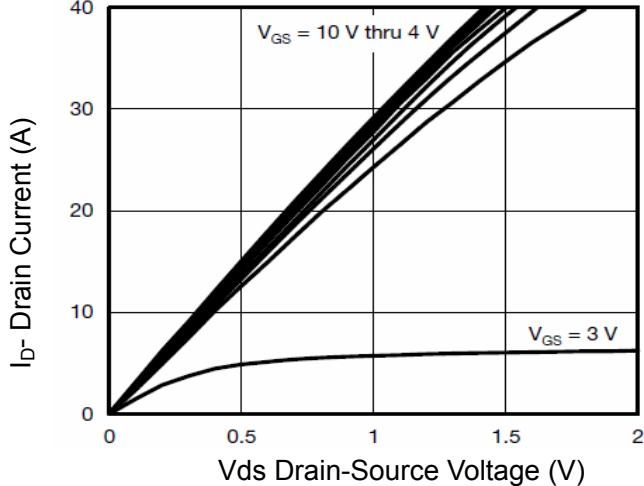
## 2) Gate Charge Test Circuit



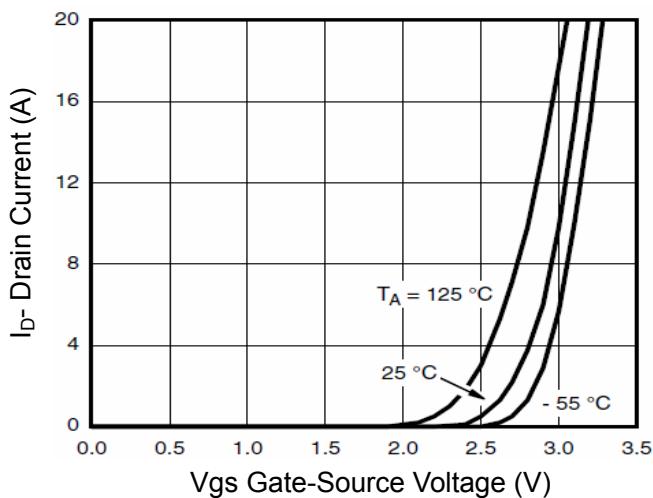
### 3) Switch Time Test Circuit



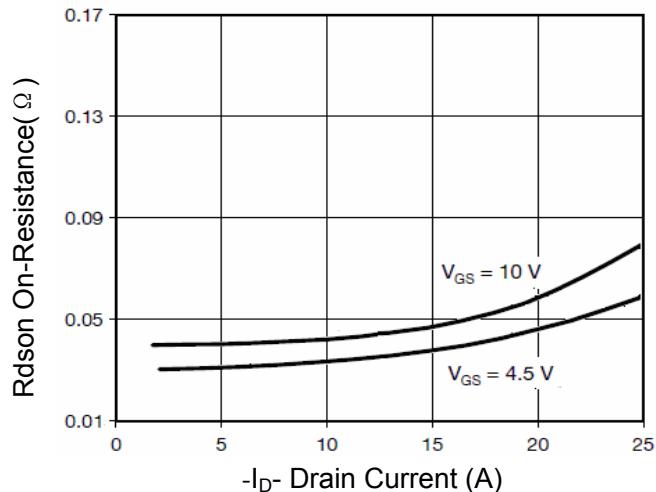
## Typical Electrical and Thermal Characteristics (Curves)



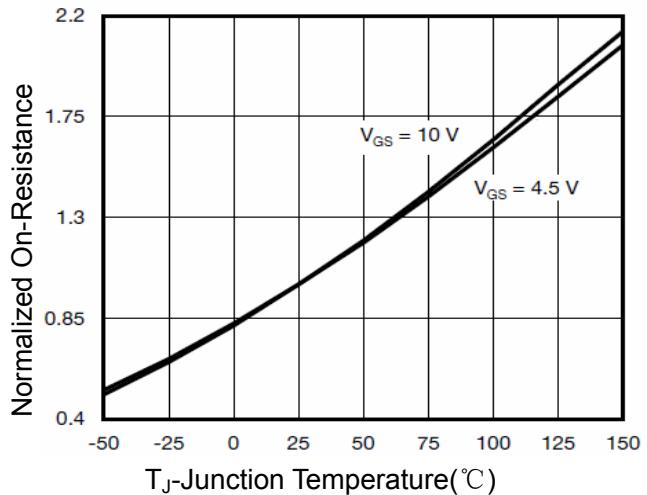
## **Figure 1 Output Characteristics**



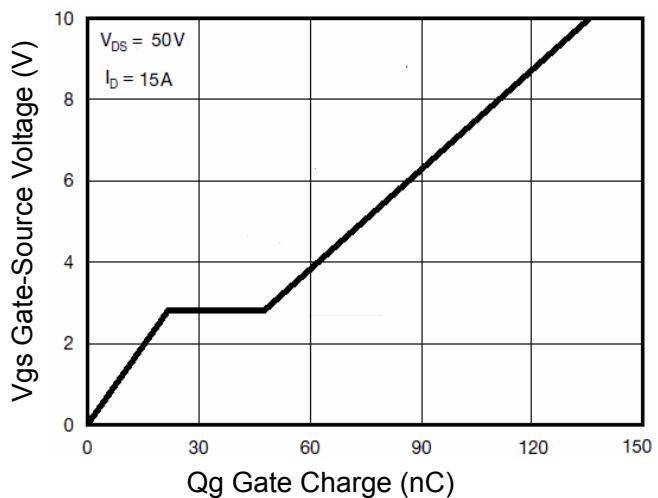
## **Figure 2 Transfer Characteristics**



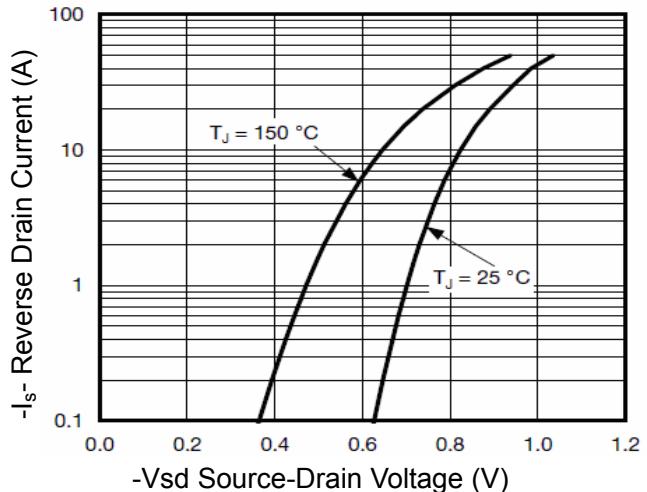
**Figure 3 Rdson- Drain Current**



## Figure 4 Rdson-JunctionTemperature



## Figure 5 Gate Charge



**Figure 6 Source- Drain Diode Forward**

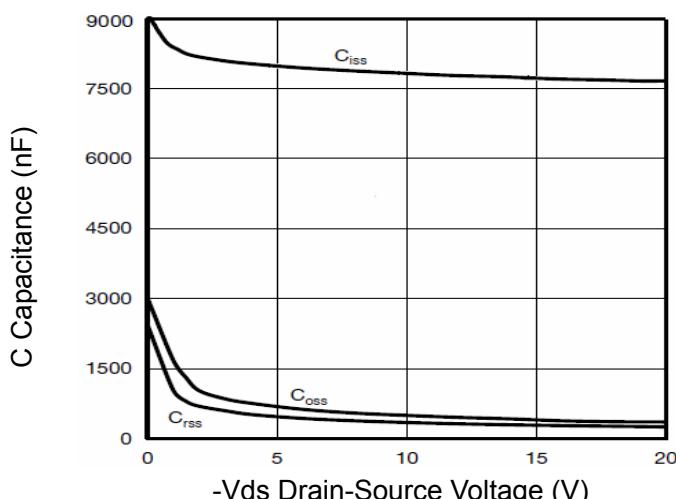


Figure 7 Capacitance vs Vds

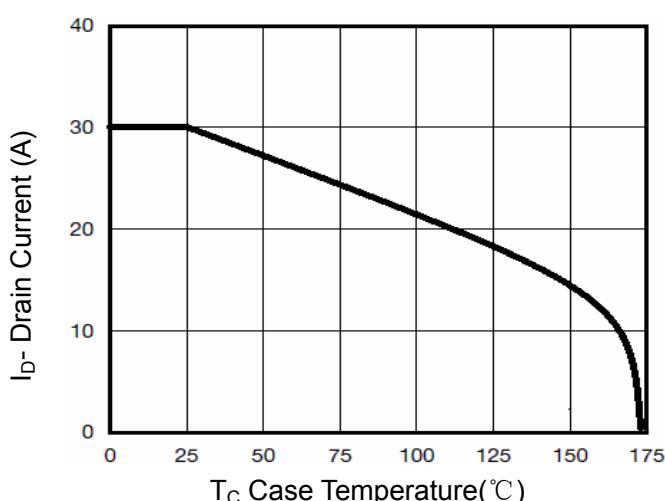


Figure 9 Drain Current vs Case Temperature

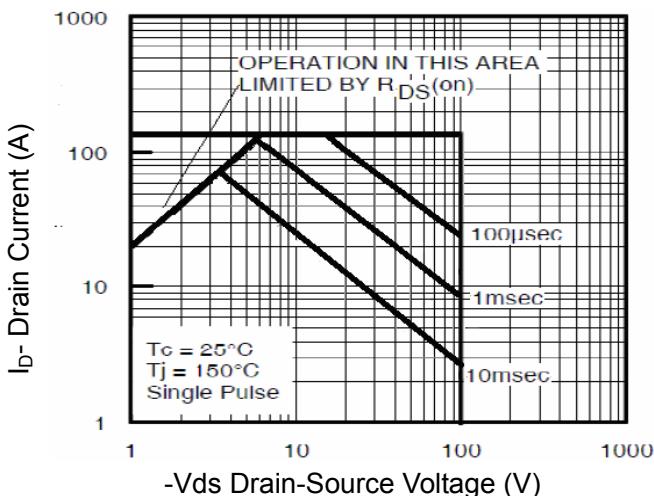


Figure 8 Safe Operation Area

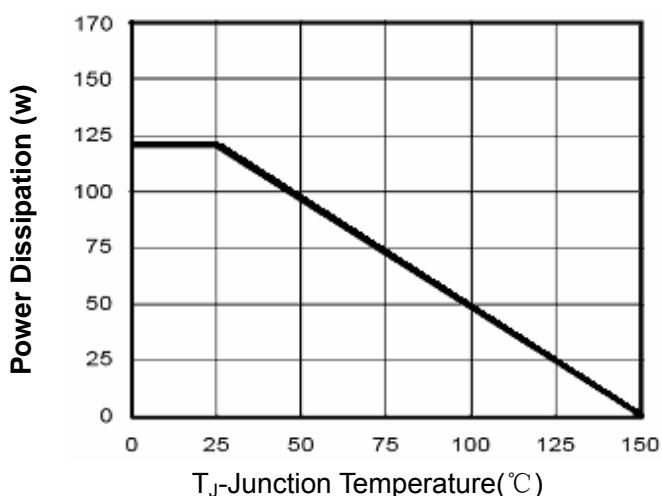


Figure 10 Power De-rating

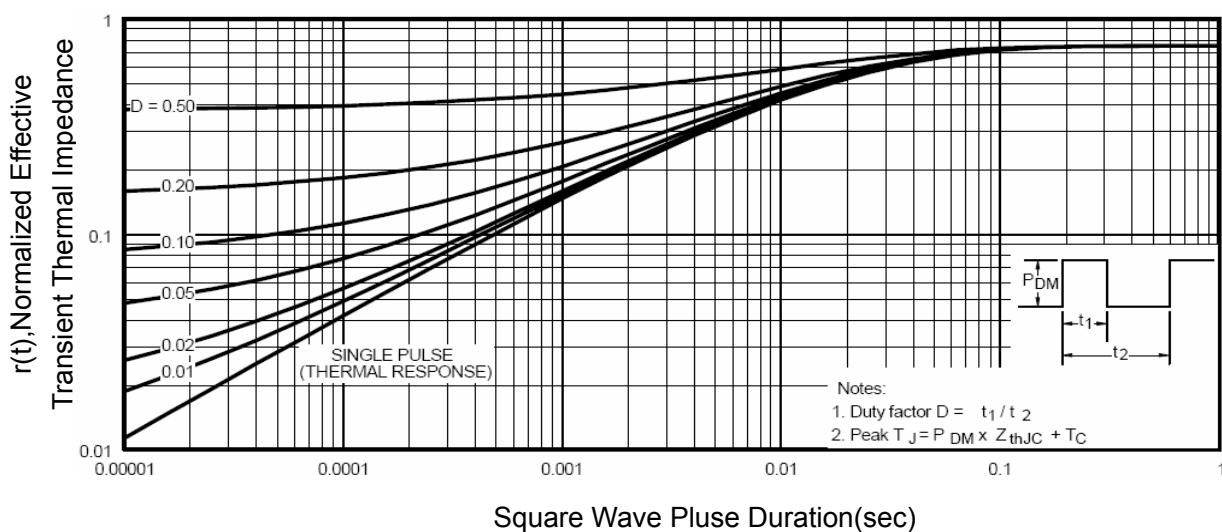
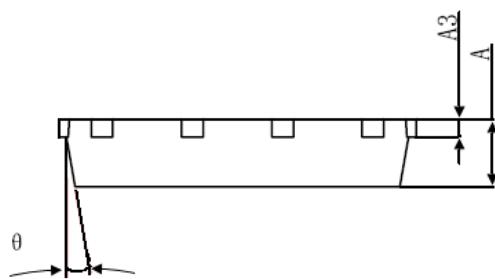
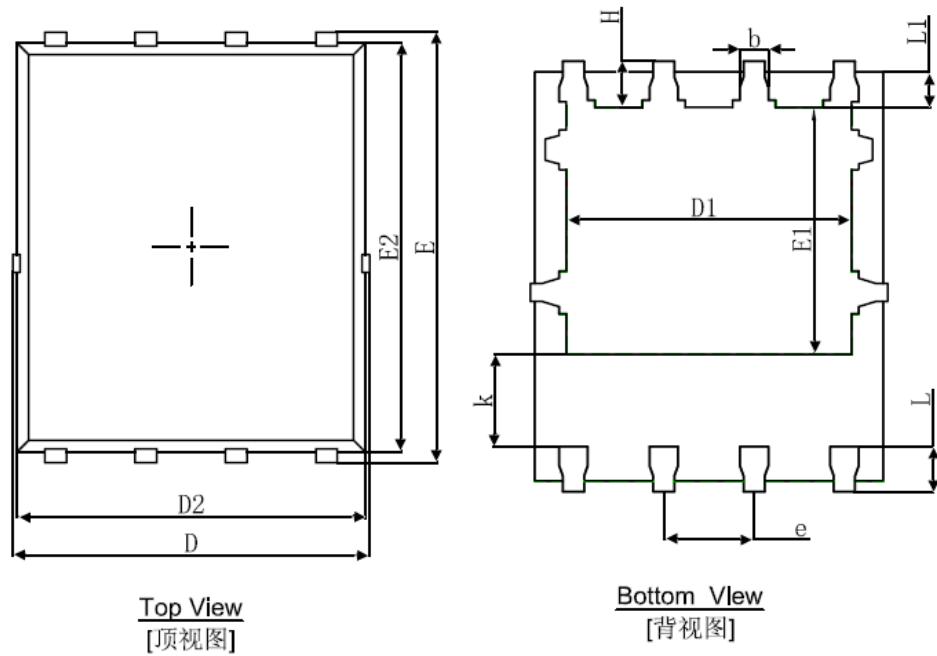


Figure 11 Normalized Maximum Transient Thermal Impedance

## **DFN5X6-8L Package Information**



Side View  
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°